

## N-Ch 60V Fast Switching MOSFETs

### Features:

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

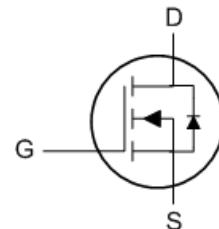


### Description:

#### SOP8 Pin Configuration

The KSCS6016 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The KSCS6016 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.



### Product Summary

BVDSS	RDSON	ID
60V	12mΩ	8A

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	8	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	6.4	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	32	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	72	mJ
I <sub>AS</sub>	Avalanche Current	38	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	85	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	24	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$ , $I_D=1\text{mA}$	---	0.052	---	$\text{V}/\text{ }^{\circ}\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=8\text{A}$	---	10.2	12	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=6\text{A}$	---	13	15	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	---	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.76	---	$\text{mV}/\text{ }^{\circ}\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55\text{ }^{\circ}\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=8\text{A}$	---	45	---	S
$R_g$	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	1.5	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=48\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=8\text{A}$	---	30	---	nC
$Q_{gs}$	Gate-Source Charge		---	10.7	---	
$Q_{gd}$	Gate-Drain Charge		---	9.4	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$ , $I_D=8\text{A}$	---	10.6	---	ns
$T_r$	Rise Time		---	9	---	
$T_{d(off)}$	Turn-Off Delay Time		---	65.6	---	
$T_f$	Fall Time		---	4.8	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3240	---	pF
$C_{oss}$	Output Capacitance		---	210	---	
$C_{rss}$	Reverse Transfer Capacitance		---	146	---	

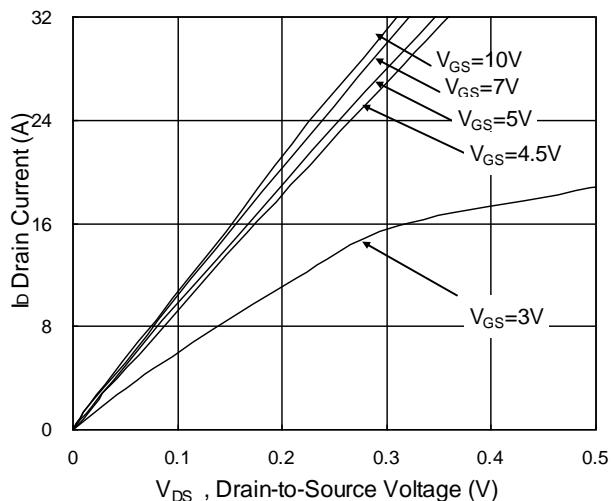
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	8	A
$I_{sM}$	Pulsed Source Current <sup>2,5</sup>		---	---	32	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=8\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	18	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	15.6	---	nC

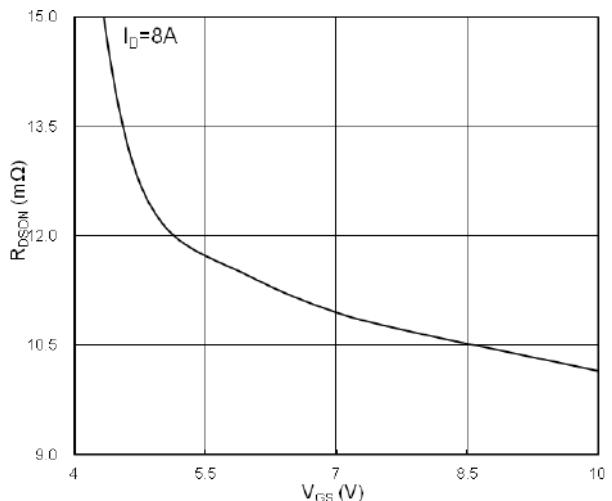
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25\text{V}$ , $V_{GS}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=38\text{A}$
- 4.The power dissipation is limited by  $150\text{ }^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

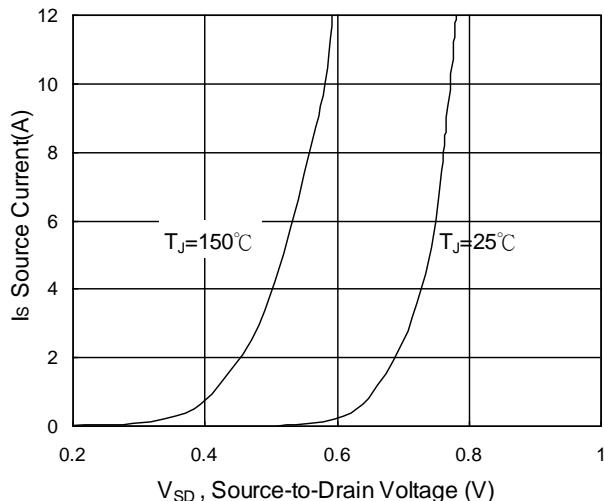
### Typical Characteristics



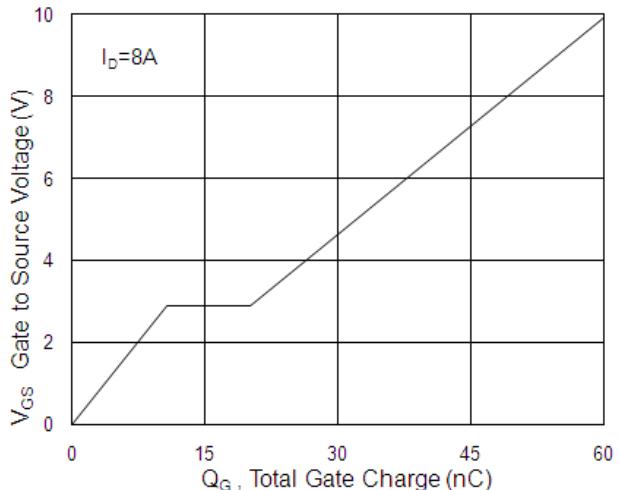
**Fig.1 Typical Output Characteristics**



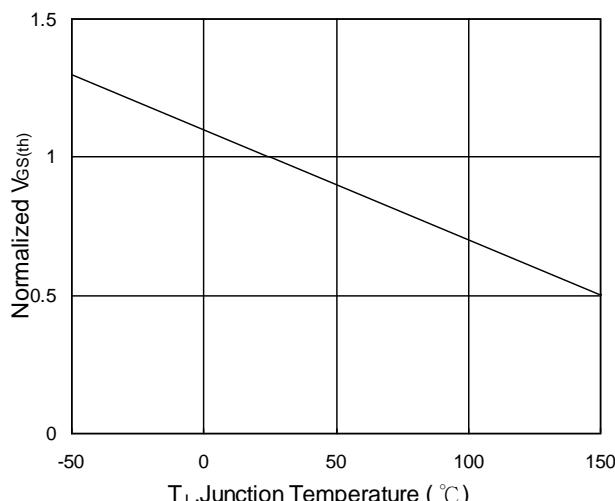
**Fig.2 On-Resistance v.s. Gate-Source**



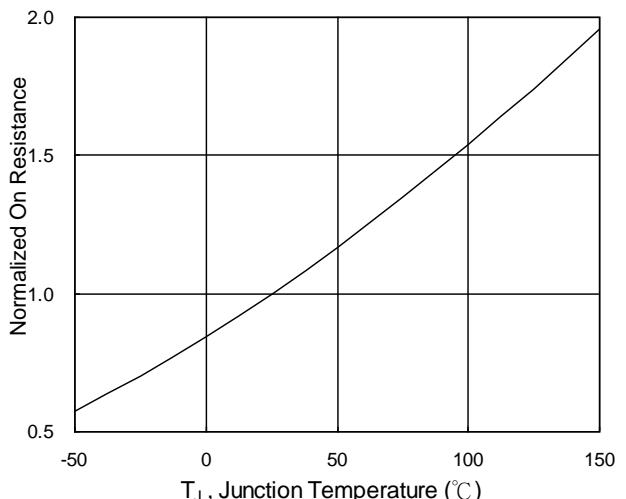
**Fig.3 Forward Characteristics of Reverse**



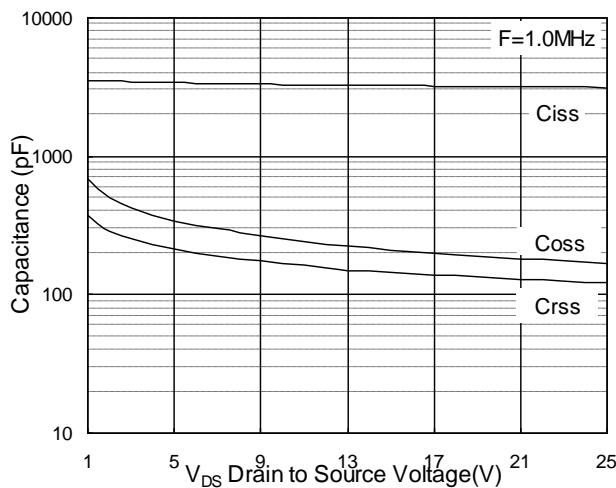
**Fig.4 Gate-Charge Characteristics**



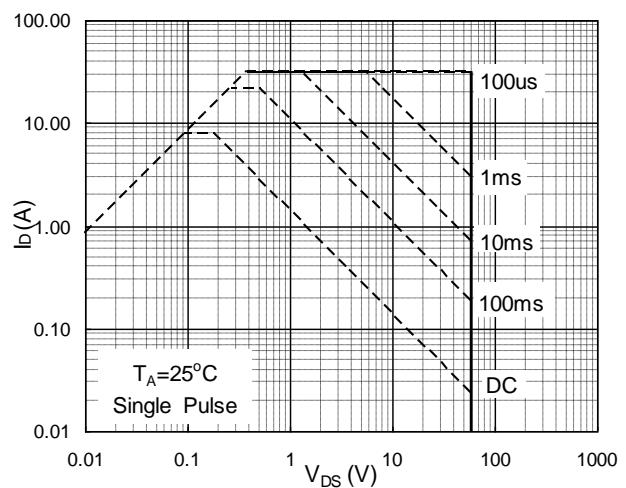
**Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>**



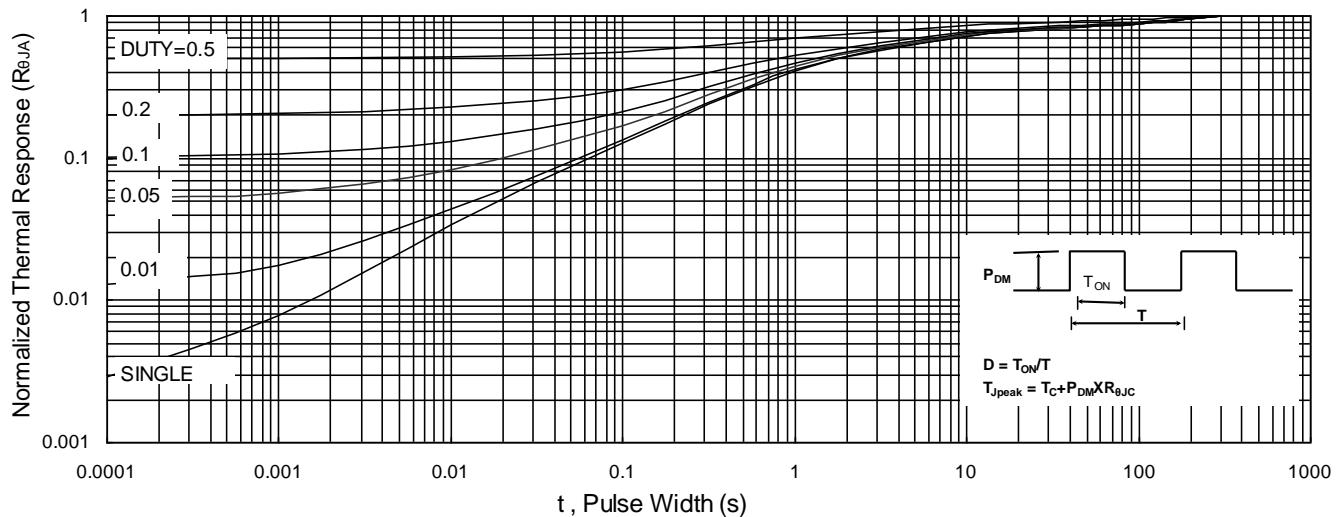
**Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>**



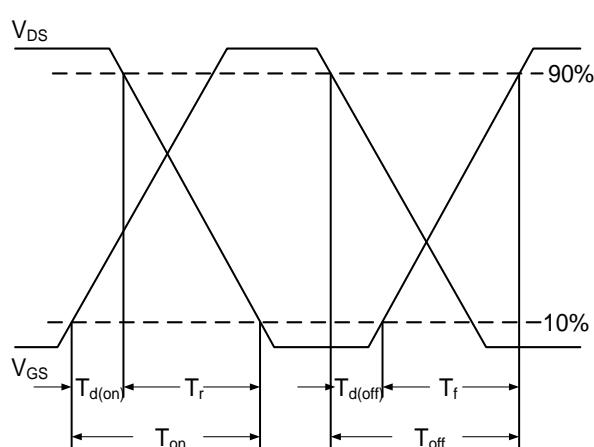
**Fig.7 Capacitance**



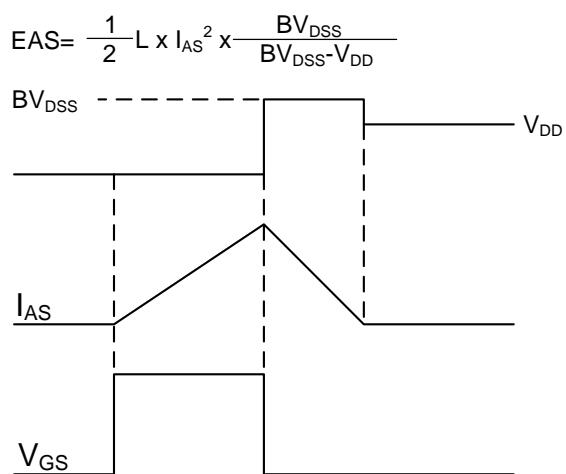
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**